

METHOD FOR MACHINING WORKPIECE

ABSTRACT

Provided is a method for machining a workpiece including a substrate that has front and back surfaces and a ductile material layer that contains a ductile material and is disposed on the front or back surface. The method includes a tape bonding step of bonding a tape on a side of the substrate of the workpiece, a holding step of holding the workpiece by a holding table via the tape, and a cutting step of relatively moving the holding table and a cutting blade to cause the cutting blade to cut into the ductile material layer and the substrate. In the cutting step, the cutting blade is rotated such that a portion of the cutting blade, the portion being located on a forward side in a moving direction of the cutting blade relative to the holding table.

[Fig. 8]